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Claims:

 A method for depositing a silicon-containing film, comprising: delivering a silicon compound to a substrate surface;

reacting the silicon compound to deposit the silicon-containing film on the substrate surface; and

the silicon compound comprising a structure:

$$X_{1} \xrightarrow{X_{2}} X_{4}$$

$$X_{1} \xrightarrow{S_{1}} R \xrightarrow{R} X_{6}$$

$$X_{3} X_{5}$$

wherein X_1 - X_6 are independently hydrogen or halogen, R is carbon, silicon or germanium and X_1 - X_6 comprise at least one hydrogen and at least one halogen.

- 2. The method of claim 1, wherein R is silicon and X_1 - X_6 are independently hydrogen or chlorine.
- 3. The method of claim 1, wherein the silicon-containing film comprises a material selected from the group consisting of silicon, silicon germanium, silicon carbon or silicon germanium carbon.
- 4. The method of claim 3, wherein the silicon-containing film is doped with an element selected from the group consisting of boron, phosphorus or arsenic.
- 5. The method of claim 3, wherein the silicon-containing film is deposited by atomic layer epitaxy, atomic layer deposition or chemical vapor deposition.
- 6. The method of claim 5, wherein a supplemental etchant is used while depositing the silicon-containing film and the supplemental etchant is selected from

Attorney Docket No.: AMAT/7729/TCG/EPI/RKK

Express Mail No.: EV321032093US

the group consisting of HCl, Cl₂, HF, HBr, XeF₂, NH₄F, (NH₄)(HF₂), NF₃ and combinations thereof.

- 7. The method of claim 5, wherein the silicon-containing film has a thickness in the range from about 2.5 Å to about 10 μ m.
- 8. The method of claim 7, wherein the at least one halogen is converted into an in-situ etchant.
- 9. A composition of matter comprising a structure:

$$X_1$$
 X_2 X_4 X_5 X_6 X_6 X_8 X_8 X_8

wherein X_1 - X_6 are independently hydrogen or halogen, R is carbon, silicon or germanium and X_1 - X_6 comprise at least one hydrogen and at least one halogen and the proviso that R is not carbon when X_4 , X_5 and X_6 are fluorine.

- 10. The composition of matter according to claim 9, wherein R is silicon and X_1 - X_6 are independently hydrogen or chlorine.
- 11. The composition of matter according to claim 9, wherein X_1 - X_6 comprise at least three hydrogens.
- 12. The composition of matter according to claim 9, wherein X_1 - X_6 comprise at least three halogens.

PATENT

Attorney Docket No.: AMAT/7729/TCG/EPI/RKK

Express Mail No.: EV321032093US

- 13. The composition of matter according to claim 9, wherein X_1 - X_6 comprise at least one chlorine and at least one atom selected from the group consisting of fluorine and bromine.
- 14. The composition of matter according to claim 13, wherein X_1 - X_6 comprise at least three halogens.
- 15. A composition of matter comprising a structure:

$$X_1 \xrightarrow{X_2} X_4$$

$$X_1 \xrightarrow{S_1} R \xrightarrow{R} X_6$$

$$X_3 X_5$$

wherein X₁-X₆ are independently hydrogen or halogen and R is germanium.

- 16. The composition of matter of claim 15, wherein X_1 - X_6 are each hydrogen.
- 17. A method for depositing a silicon-containing film, comprising: delivering a silicon compound to a substrate surface;

reacting the silicon compound to deposit the silicon-containing film on the substrate surface; and

the silicon compound comprising structures:

$$X_1$$
 X_2
 X_3
 X_4
 X_6
 X_5

Attorney Docket No.: AMAT/7729/TCG/EPI/RKK

Express Mail No.: EV321032093US

wherein X_1 - X_8 are independently hydrogen or halogen, R is carbon, silicon or germanium and X_1 - X_8 comprise at least one halogen.

- 18. The method of claim 17, wherein R is silicon and X_1 - X_8 are independently hydrogen or chlorine.
- 19. The method of claim 17, wherein the silicon-containing film comprises a material selected from the group consisting of silicon, silicon germanium, silicon carbon or silicon germanium carbon.
- 20. The method of claim 19, wherein the silicon-containing film is doped with an element selected from the group consisting of boron, phosphorus or arsenic.
- 21. The method of claim 19, wherein the silicon-containing film is deposited by atomic layer epitaxy, atomic layer deposition or chemical vapor deposition.
- 22. The method of claim 17, wherein X_1 - X_8 comprise at least three hydrogen atoms.
- 23. The method of claim 17, wherein X_1 - X_8 comprise at least three halogen atoms.
- 24. The method of claim 21, wherein a supplemental etchant is used while depositing the silicon-containing film and the supplemental etchant is selected from the group consisting of HCl, Cl₂, HF, HBr, XeF₂, NH₄F, (NH₄)(HF₂), NF₃ and combinations thereof.

PATENT

Attorney Docket No.: AMAT/7729/TCG/EPI/RKK

Express Mail No.: EV321032093US

- 25. The method of claim 21, wherein the silicon-containing film has a thickness in the range from about 2.5 Å to about 10 μ m.
- 26. The method of claim 25, wherein the at least one halogen is converted into an in-situ etchant.
- 27. A composition of matter comprising structures:

$$X_1$$
 X_2
 X_3
 X_4
 X_6
 X_5

$$X_1$$
 X_2 X_4 X_6 X_1 X_2 X_4 X_6 X_8 X_1 X_2 X_3 X_5 X_7 X_8 X_1 X_2 X_3 X_5 X_7

wherein X_1 - X_8 are independently hydrogen or halogen, R is carbon, silicon or germanium and X_1 - X_8 comprise at least one halogen.

- 28. The composition of matter according to claim 27, wherein R is silicon and X_1 - X_8 are independently hydrogen or chlorine.
- 29. The composition of matter according to claim 27, wherein X_1 - X_8 comprise at least three hydrogens.
- 30. The composition of matter according to claim 27, wherein X_1 - X_8 comprise at least three halogens.

Attorney Docket No.: AMAT/7729/TCG/EPI/RKK

Express Mail No.: EV321032093US

- 31. The composition of matter according to claim 27, wherein X_1 - X_8 comprise at least one chlorine and at least one atom selected from the group consisting of fluorine and bromine.
- 32. The composition of matter according to claim 31, wherein X_1 - X_8 comprise at least three halogens.
- 33. A composition of matter comprising structures:

$$X_1$$
 X_2
 X_3
 X_4
 X_6
 X_5

wherein X₁-X₈ are independently hydrogen or halogen and R is germanium.

- 34. The composition of matter according to claim 33, wherein X_1 - X_8 are each hydrogen.
- 35. A method for depositing a silicon-containing film, comprising: delivering a silicon compound to a substrate surface;

reacting the silicon compound to deposit the silicon-containing film on the

substrate surface; and

the silicon compound comprising structures of compounds 1-8, wherein X_{1-} X_{10} are independently hydrogen or halogen, R is carbon, silicon or germanium and $X_{1-}X_{10}$ comprise at least one halogen.

36. The method of claim 35, wherein R is silicon and X_1-X_{10} are independently

hydrogen, chlorine or fluorine.

37. The method of claim 35, wherein the silicon-containing film comprises a

material selected from the group consisting of silicon, silicon germanium, silicon

carbon or silicon germanium carbon.

38. The method of claim 37, wherein the silicon-containing film is doped with an

element selected from the group consisting of boron, phosphorus or arsenic.

39. The method of claim 37, wherein the silicon-containing film is deposited by

atomic layer epitaxy, atomic layer deposition or chemical vapor deposition.

40. The method of claim 39, wherein a supplemental etchant is used while

depositing the silicon-containing film and the supplemental etchant is selected from

the group consisting of HCl, Cl₂, HF, HBr, XeF₂, NH₄F, (NH₄)(HF₂), NF₃ and

combinations thereof.

41. The method of claim 39, wherein the silicon-containing film has a thickness in

the range from about 2.5 Å to about 10 μ m.

42. The method of claim 41, wherein the at least one halogen is converted into an

in-situ etchant.

43. A composition of matter comprising structures of compounds 1-8, wherein X₁-

X₁₀ are independently hydrogen or halogen, R is carbon, silicon or germanium and

 X_1 - X_{10} comprise at least one halogen.

44. The composition of matter according to claim 43, wherein R is silicon and X₁-

 X_{10} are independently hydrogen or chlorine.

47

45. The composition of matter according to claim 43, wherein X_1 - X_{10} comprise at least one chlorine and at least one atom selected from the group consisting of fluorine and bromine.

- 46. The composition of matter according to claim 45, wherein X_1 - X_{10} comprise at least three halogens.
- 47. A composition of matter comprising structures of compounds 1-8, wherein X_{1-} X_{10} are independently hydrogen or halogen and R is germanium.
- 48. The composition of matter according to claim 47, wherein X_1 - X_{10} are each hydrogen.
- 49. A method for depositing a silicon-containing film, comprising: delivering a silicon compound to a substrate surface;

reacting the silicon compound to deposit the silicon-containing film on the substrate surface; and

the silicon compound comprising structures of compounds 9-32, wherein X_{1-} X_{12} are independently hydrogen or halogen and R is carbon, silicon or germanium.

- 50. The method of claim 49, wherein R is silicon and X_1 - X_{12} are independently hydrogen or chlorine.
- 51. The method of claim 49, wherein the silicon-containing film comprises a material selected from the group consisting of silicon, silicon germanium, silicon carbon or silicon germanium carbon.
- 52. The method of claim 51, wherein the silicon-containing film is doped with an element selected from the group consisting of boron, phosphorus or arsenic.

53. The method of claim 51, wherein the silicon-containing film is deposited by

atomic layer epitaxy, atomic layer deposition or chemical vapor deposition.

54. The method of claim 49, wherein X_1-X_{12} comprise at least three hydrogen

atoms.

55. The method of claim 49, wherein X_1 - X_{12} comprise at least three halogen

atoms.

56. The method of claim 53, wherein a supplemental etchant is used while

depositing the silicon-containing film and the supplemental etchant is selected from

the group consisting of HCl, Cl₂, HF, HBr, XeF₂, NH₄F, (NH₄)(HF₂), NF₃ and

combinations thereof.

57. The method of claim 53, wherein the silicon-containing film has a thickness in

the range from about 2.5 Å to about 10 μ m.

58. The method of claim 57, wherein the at least one halogen is converted into an

in-situ etchant.

59. A composition of matter comprising structures of compounds 9-32, wherein

X₁-X₁₂ are independently hydrogen or halogen, R is carbon, silicon or germanium

and X_1 - X_{12} comprise at least one halogen.

60. The composition of matter according to claim 59, wherein R is silicon and X₁-

X₁₂ are independently hydrogen or chlorine.

61. The composition of matter according to claim 59, wherein X_1 - X_{12} comprise at

least three hydrogens.

49

62. The composition of matter according to claim 59, wherein X_1 - X_{12} comprise at least three halogens.

- 63. The composition of matter according to claim 59, wherein X_1 - X_{12} comprise at least one chlorine and at least one atom selected from the group consisting of fluorine and bromine.
- 64. The composition of matter according to claim 63, wherein X_{1} - X_{12} comprise at least three halogens.
- 65. A composition of matter comprising structures of compounds 9-32, wherein X_{1} - X_{12} are independently hydrogen or halogen and R is germanium.
- 66. The composition of matter according to claim 65, wherein X_1 - X_{12} are each hydrogen.